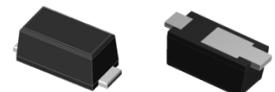


Features

- Heatsink structure
- Low profile, typical thickness 0.8mm
- Low forward voltage drop
- Super low VF schottky barrier diodes
- Moisture sensitivity: level 1, per J-STD-020
- High temperature soldering guaranteed: 260°C/10 seconds



Package: iSGA
 (SOD-123HS)



RoHS
 COMPLIANT

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	GSPS22	GSPS23	GSPS24	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	V
Maximum RMS voltage	V_{RMS}	14	21	28	V
Maximum DC blocking voltage	V_{DC}	20	30	40	V
Maximum average forward rectified current	$I_{F(AV)}$	2.0			A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	50			A
Rating for fusing($t < 8.3\text{ms}$)	I^2t	10			A^2sec
Operating junction temperature range	T_J	- 55 to + 150			°C
Storage temperature range	T_{STG}	- 55 to + 150			°C

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Test Conditions	Symbol	GSPS22	GSPS23	GSPS24	Unit	
Minimum Breakdown voltage	$T_A=25^\circ\text{C}, I_R=1\text{mA}$	V_{BR}	20	30	40	V	
Maximum instantaneous forward voltage	$I_F=2\text{A } T_A=25^\circ\text{C}$	V_F	0.51				
	$I_F=2\text{A } T_A=125^\circ\text{C}$	V_F	0.45				
Maximum DC reverse current at rated DC blocking voltage	$T_A=25^\circ\text{C}$	I_R	50			uA	
	$T_A=125^\circ\text{C}$		15			mA	
Typical junction capacitance	4.0 V, 1 MHz	C_J	120			pF	
Typical thermal resistance ¹⁾	junction to ambient	$R_{\theta JA}$	110			°C/W	
	junction to case	$R_{\theta JC}$	20				
	junction to lead	$R_{\theta JL}$	15				

Note:1)The thermal resistance from junction to ambient,case or lead,mounted on FR-4 P.C.B

Typical Electrical Characteristic Curves

($T_A = 25^\circ\text{C}$ unless otherwise noted)

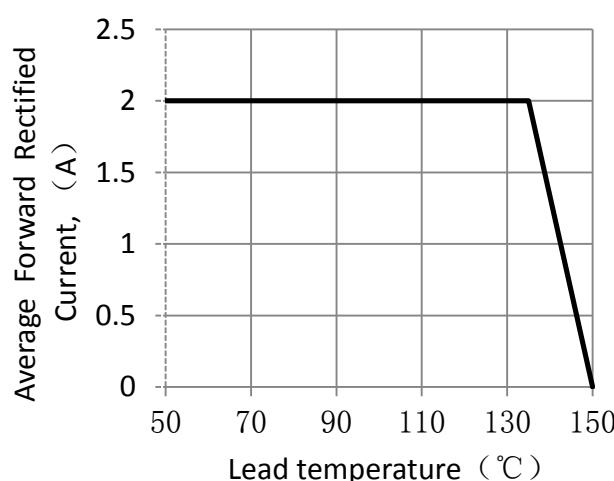


Figure 1. Forward Current Derating Curve

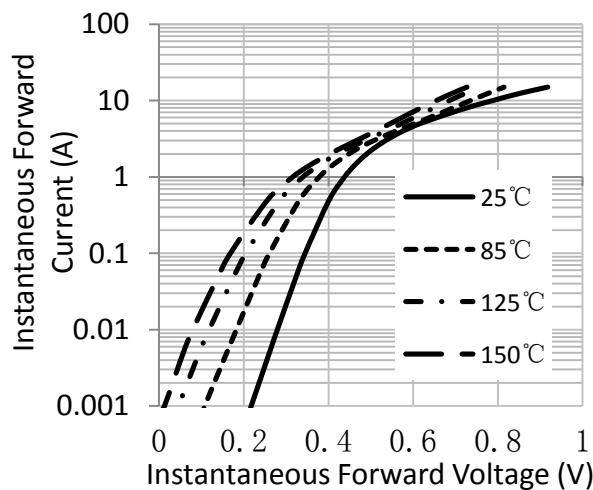


Figure 3. Typical Instantaneous Forward Characteristics

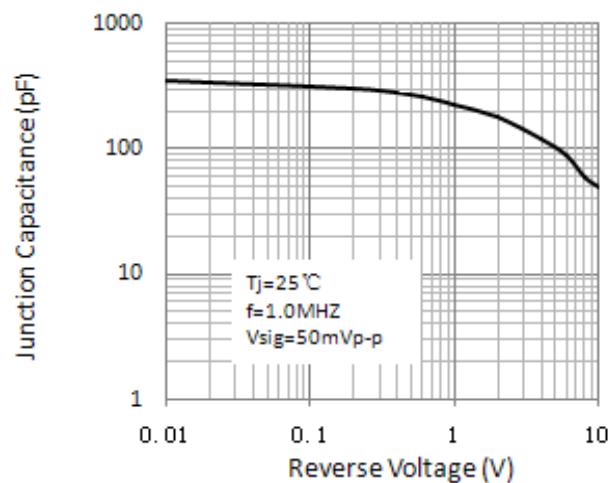


Figure 5. Typical Junction Capacitance

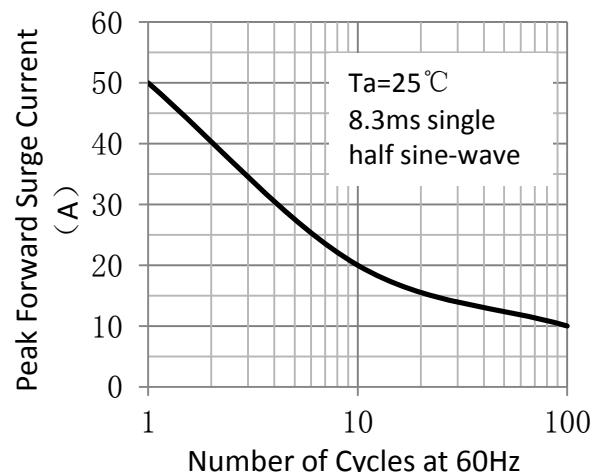


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

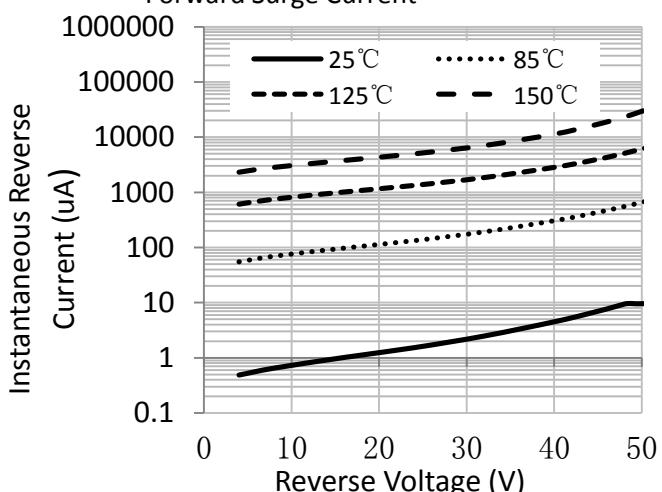
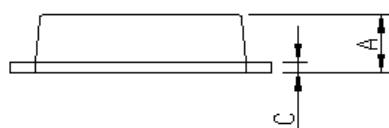
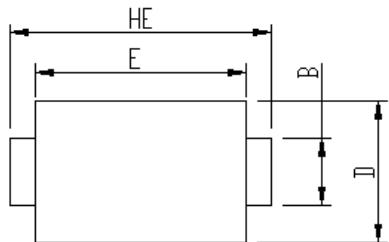


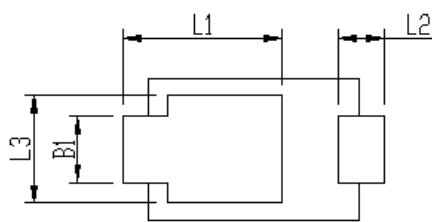
Figure 4. Typical Reverse Characteristics

Package Outline Dimensions



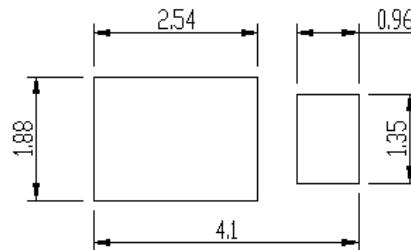
Package: iSGA

(SOD-123HS)



Package	iSGA	
Unit:mm	MIN	MAX
A	0.75	0.90
B	0.85	1.05
B1	0.85	1.05
C	0.1	0.25
D	1.9	2.1
E	2.9	3.1
L1	2.0	2.45
L2	0.4	0.85
L3	1.3	1.7
HE	3.5	3.9

Soldering footprint



Order Information

Device	Package	Marking	Carrier	Quantity
GSPS22	iSGA (SOD-123HS)	PS22	Tape & Reel	3,000pcs / Reel
GSPS23	iSGA (SOD-123HS)	PS23	Tape & Reel	3,000pcs / Reel
GSPS24	iSGA (SOD-123HS)	PS24	Tape & Reel	3,000pcs / Reel